

# TP 2520 Series (Preliminary)

## Multilayer Chip Triplexers

### Features

- ❖ Monolithic structure including one low-pass ,and two band-pass filters with loss pole at adjacent passband.
- ❖ RoHS compliant

### Applications

- ❖ Wireless communication

### Specifications

Part Number	Passband (MHz)	Insertion Loss (dB)	VSWR	Attenuation (dB)
<b>TP2520-A081831NA</b>	698~960	1.0 typ.	2 Max.	10 min. @ 1425 ~ 2170MHz 10 min. @ 2496 ~ 3800MHz
	1425~2170	1.5 typ.	2 Max.	10 min. @ 698 ~ 960MHz 10 min. @ 2496 ~ 3800MHz
	2496~3800	1.6 typ.	2 Max.	10 min. @ 698 ~ 960MHz 10 min. @ 1425 ~ 2170MHz

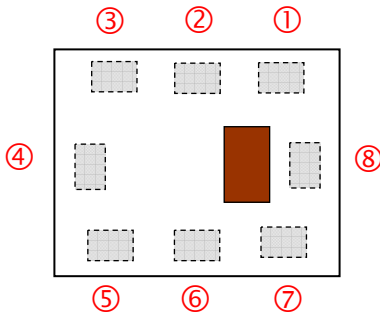
Q'ty/Reel (pcs) : 3000  
 Operating Temperature Range : -40 ~ +85 °C  
 Storage Temperature Range : -40 ~ +85 °C  
 Storage Period : 12 months max.  
 Power Capacity : 3W max.

### Part Number

TP   2520   -   A   081831   NA   □   /LF  
 ①   ②   ③   ④   ⑤   ⑥   ⑦

① Type	TP : Triplexer	② Dimensions ( L × W )	2.5 × 2.0 mm
③ Material Code	A	④ Frequency Range	081831=800MHz /1800MHz/3100MHz
⑤ Specification Code	NA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

## Terminal Configuration

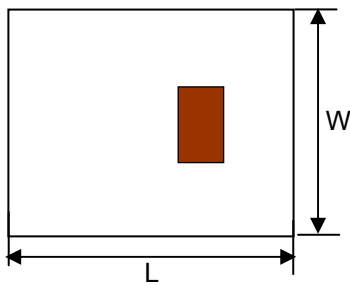


<Top View>

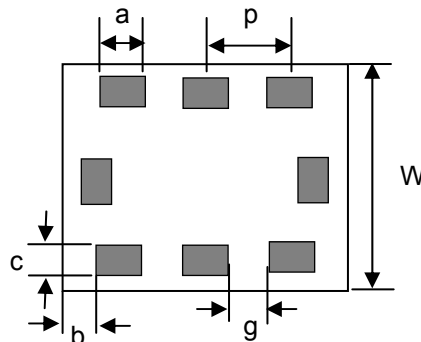
No.	Terminal Name	No.	Terminal Name
①	GND	⑤	GND
②	Common Port	⑥	M.B. Port
③	GND	⑦	GND
④	H.B. Port	⑧	L.B. Port

## Dimensions and Recommended PC Board Pattern

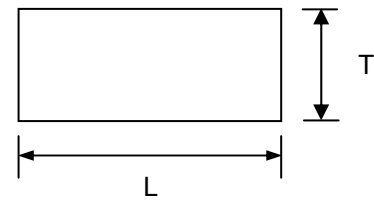
Unit : mm



<Top View>

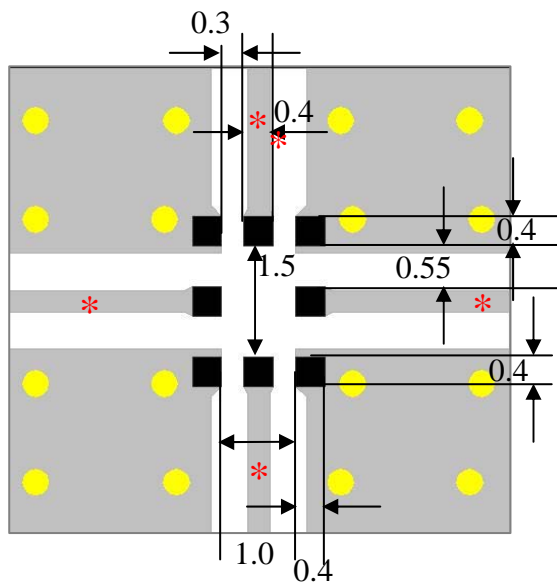


<Bottom View>



<Side View>

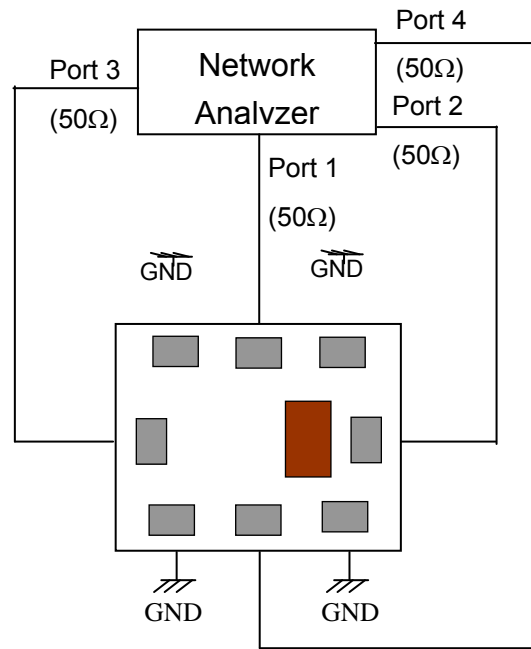
Mark	L	W	T	a	b	c	g	p
Dimensions	2.5 ± 0.2	2.0 ± 0.2	1.1 ± 0.1	0.4 ± 0.1	0.35 ± 0.1	0.3 + 0.1 / - 0.2	0.3 ± 0.1	0.7 ± 0.1



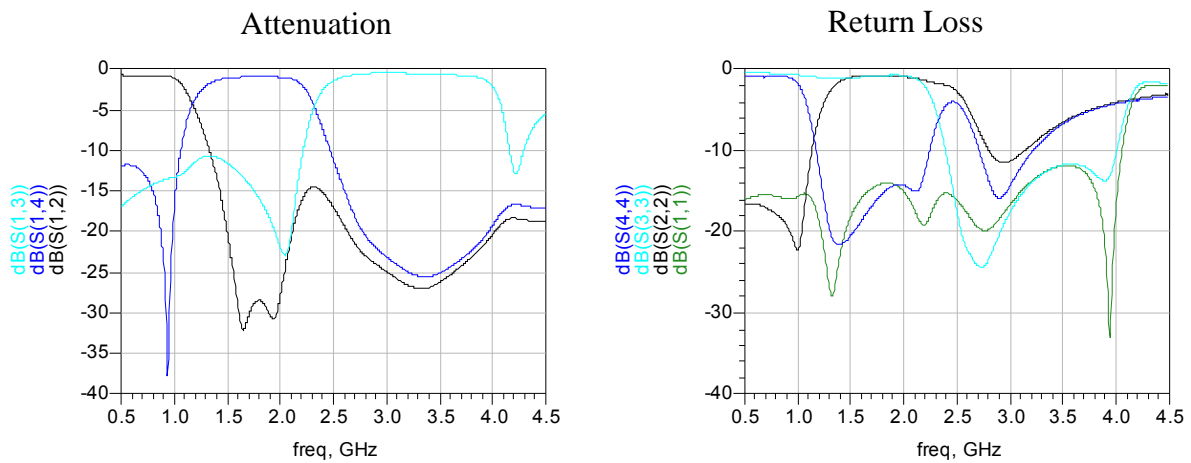
- Solder Resist
- Land
- Through-hole ( $\phi$  0.35)

\* Line width should be designed to match 50ohm characteristic impedance, depending on PCB material and thickness.

## Measuring Diagram



## Typical Electrical Characteristics

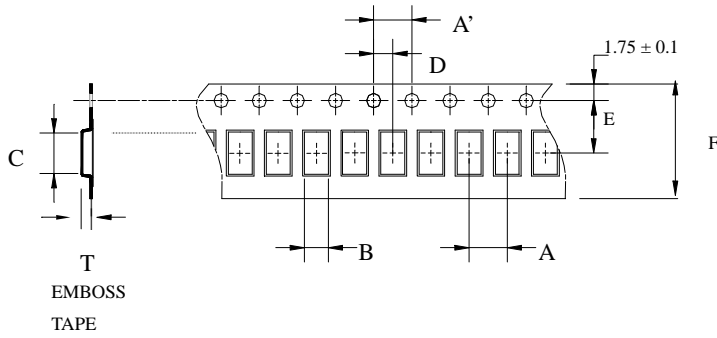


## Notes

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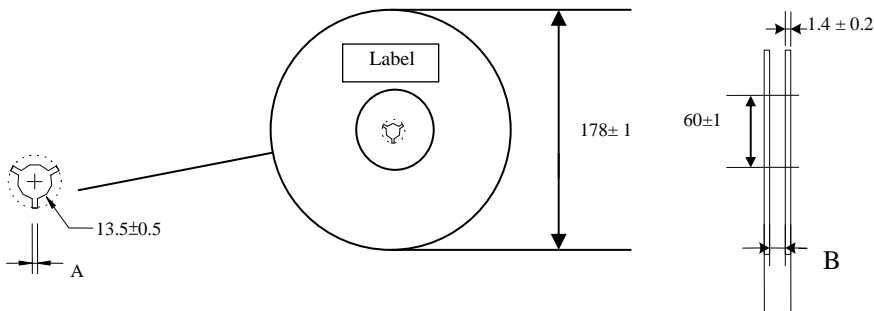
## Taping Specifications

### ❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
2520	4.0±	4.0±	2.45±	2.95±	2.0±	3.5±	8.0±	1.45±	3,000pcs	Plastic (Embossed)
	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.05		

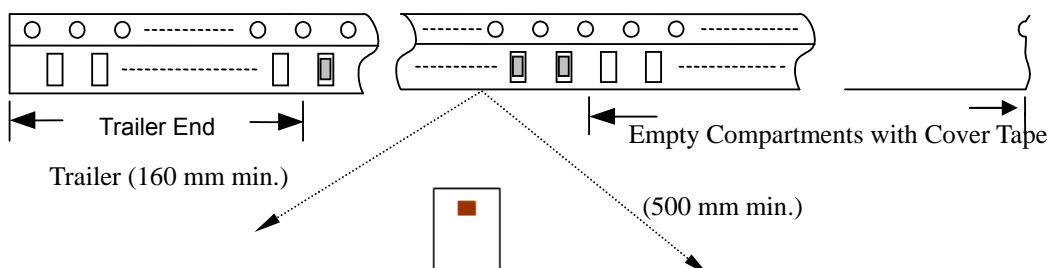
### ❖Reel Dimensions (Unit: mm)



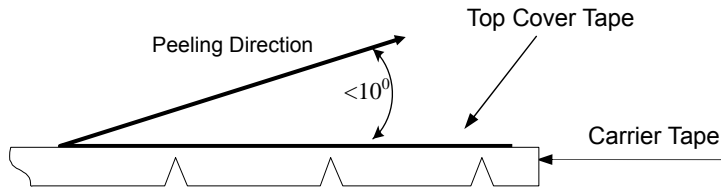
Label: Customer's Name,  
ACX P/N, Q'ty, Date,  
ACX Corp.

Type	A	B
2520	2.3±0.5	9.0±0.3

### ❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of  $300 \pm 10$  mm/min .

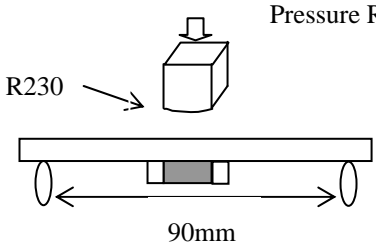
❖ **Storage Conditions**

- (1) Temperature: 5 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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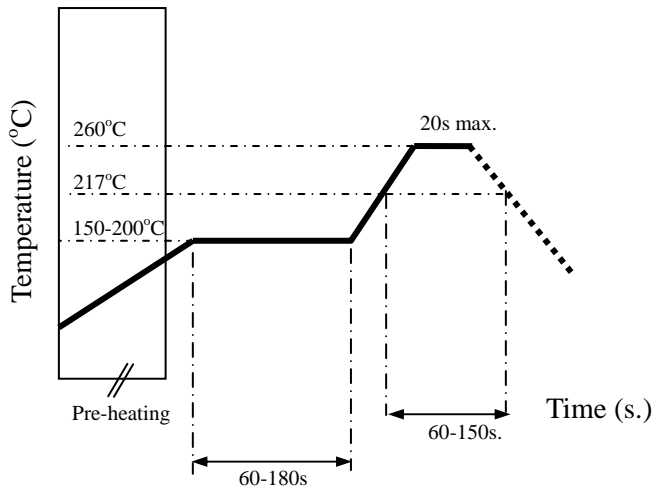
## Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> <li>1. No apparent damage</li> <li>2. More than 95% of the terminal electrode shall be covered with new solder</li> </ol>	<ol style="list-style-type: none"> <li>1. Preheat: <math>120 \pm 5^\circ\text{C}</math></li> <li>2. Solder: <math>245 \pm 5^\circ\text{C}</math> for <math>5 \pm 1</math> sec</li> </ol>
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> <li>1. 1kg minimum</li> </ol>	<ol style="list-style-type: none"> <li>1. Solder specimen onto test jig.</li> <li>2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction</li> </ol>
Deflection (Substrate Bending)	<ol style="list-style-type: none"> <li>1. No apparent damage</li> </ol>	<ol style="list-style-type: none"> <li>1. Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile.</li> <li>2. Apply a bending force of 2mm deflection</li> </ol> 
Heat/Humidity Resistance	<ol style="list-style-type: none"> <li>1. No apparent damage</li> <li>2. Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>1. Temperature: <math>85 \pm 2^\circ\text{C}</math></li> <li>2. Humidity: 90% ~ 95% RH</li> <li>3. Duration: <math>1000 \pm 48</math>hrs</li> <li>4. Recovery: 1-2hrs</li> </ol>
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> <li>1. No apparent damage</li> <li>2. Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>1. One cycle/step 1 : <math>125 \pm 5^\circ\text{C}</math> for 30 min step 2 : <math>-40 \pm 5^\circ\text{C}</math> for 30 min</li> <li>2. No of cycles : 100</li> <li>3. Recovery: 1-2 hrs</li> </ol>
Low Temperature Resistance	<ol style="list-style-type: none"> <li>1. No apparent damage</li> <li>2. Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>1. Temperature: <math>-40 \pm 5^\circ\text{C}</math></li> <li>2. Duration: <math>500 \pm 24</math>hrs</li> <li>3. Recovery: 1-2hrs</li> </ol>

## Soldering Conditions

### ❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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